

Andromeda ADM6/ADF6 B2B Connectors

The Andromeda modules use Samtec AcceleRate HD High-Density on bottom side.

- ADM6-60-01.5-L-4-2 (compatible to ADF6-60-03.5-L-4-2), (240 pins, "60" per row)

The Andromeda carriers use Samtec AcceleRate HD High-Density on top side.

- ADF6-60-03.5-L-4-2 (compatible to ADF6-60-01.5-L-4-2), (240 pins, "60" per row)

Features

- Board-to-Board Connector 240-pins, 60 contacts per row
- 0.025" (0.635 mm) pitch
- Data Rate: max 56 Gbps
- Mates with: ADM6/APF6
- Insulator Material: LCP, Black
- Contact Material: Copper Alloy
- Plating: Au or Sn over 50 μ" (1.27 μm) N
- Operating Temperature Range: -55 °C to +125 °C
- PCIe 5.0 capable: Yes
- Lead-Free Solderable: Yes
- RoHS Compliant: Yes

Connector Mating height

When using the same type on baseboard, the mating height is 5mm. Other mating heights are possible by using connectors with a different height

Order number	Connector on baseboard	compatible to	Mating height
30095	REF-30095	ADM6-60-01.5-L-4-2	5 mm
31137	REF-31137	ADF6-60-03.5-L-4-2	5 mm

Connectors.

The module can be manufactured using other connectors upon request.

Connector Speed Ratings

The AcceleRate HD High-Density connector speed rating depends on the stacking height; please see the following table:

Stacking height	Speed rating
5 mm	10/ 25/ 56 Gbps

Speed rating.

Current Rating

Current rating of Samtec AcceleRate HD High-Density B2B connectors is 1.34 A per pin (4 pins powered)

Connector Mechanical Ratings

- Shock: 100G, 6 ms Sine
- Vibration: 7.5G random, 2 hours per axis, 3 axes total

Manufacturer Documentation

File	Modified

PDF File 20200225_hsc_adm6-xx-01p5-xxx-4-a_adf6-xx-03p5-xxx-4-a.pdf	04 03, 2022 by ED
PDF File adf6.pdf	04 03, 2022 by ED
PDF File adm6.pdf	04 03, 2022 by ED
PDF File adm6-xxx-xx.x-xxx-4-x-x-xr-mkt.pdf	04 03, 2022 by ED
PDF File adm6-xxx-xx.x-xxx-x-x-x-footprint.pdf	04 03, 2022 by ED

[Download All](#)